

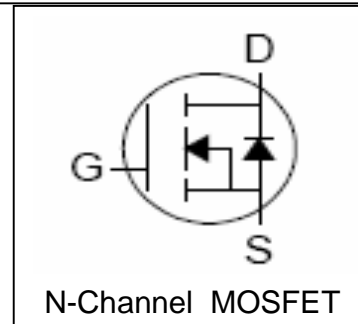
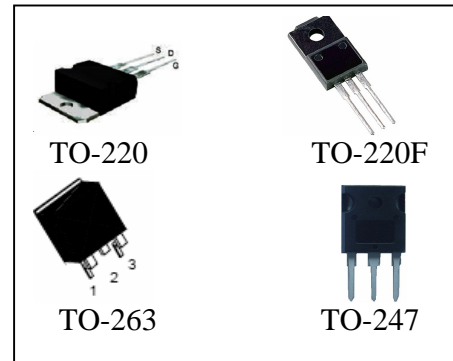
## Features

- 80V/190A  
 $R_{DS(ON)}=3.9m\Omega(Typ.) @ V_{GS}=10V$
- Avalanche Rated
- Reliable and Rugged
- Lead Free and Green Devices Available

## Applications

- Automotive applications and a wide variety of other applications
- High Efficiency Synchronous in SMPS
- High Speed Power Switching

## Pin Description



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
<b>Common Ratings</b> ( $T_A=25^\circ\text{C}$ Unless Otherwise Noted)			
$V_{DSS}$	Drain-Source Voltage	80	V
$V_{GSS}$	Gate-Source Voltage	$\pm 25$	
$T_J$	Maximum Junction Temperature	175	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ 190	A
<b>Mounted on Large Heat Sink</b>			
$I_{DP}$	300 $\mu\text{s}$ Pulsed Drain Current Tested	$T_C=25^\circ\text{C}$ 700 <sup>①</sup>	A
$I_D$	Continue Drain Current	$T_C=25^\circ\text{C}$ 190 <sup>②</sup>	
		$T_C=100^\circ\text{C}$ 140	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$ 400	W
		$T_C=100^\circ\text{C}$ 220	
$R_{\theta JC}$	Thermal Resistance -Junction to Case	0.45	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	62.5	
<b>Drain-Source Avalanche Ratings</b>			
$E_{AS}$	Avalanche Energy ,Single Pulsed	2000	mJ

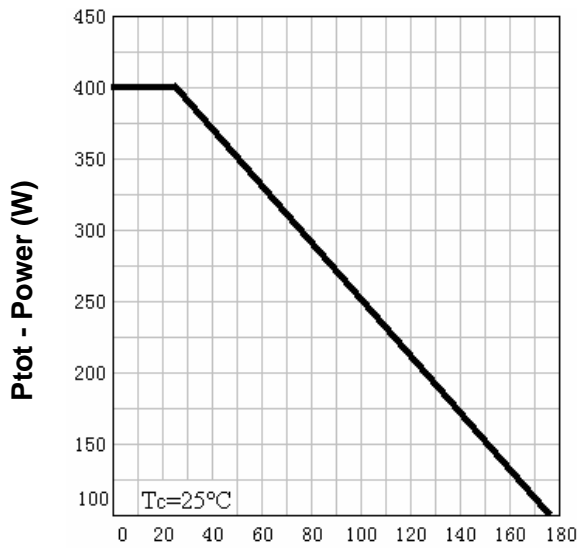
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  Unless Otherwise Noted)

Symbol	Parameter	Test Condition	RU190N08			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	80			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$ $T_J=85^\circ\text{C}$			1	$\mu A$
					30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	2	3	4	V
$I_{GSS}$	Gate Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$			$\pm 100$	nA
$R_{DS(ON)}^{(3)}$	Drain-Source On-state Resistance	$V_{GS}=10V, I_{DS}=40A$		3.9	4.8	m $\Omega$
<b>Diode Characteristics</b>						
$V_{SD}^{(3)}$	Diode Forward Voltage	$I_{SD}=40A, V_{GS}=0V$		0.8	1.3	V
$t_{rr}$	Reverse Recovery Time	$I_{SD}=40A, dI_{SD}/dt=100A/\mu s$		68		ns
$q_{rr}$	Reverse Recovery Charge			130		nC
<b>Dynamic Characteristics</b> <sup>(4)</sup>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		1.0		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V,$ $V_{DS}=30V,$ Frequency=1.0MHz		6800		pF
$C_{oss}$	Output Capacitance			1100		
$C_{rss}$	Reverse Transfer Capacitance			490		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=35V, R_L=35\Omega,$ $I_{DS}=1A, V_{GEN}=10V,$ $R_G=6\Omega$		38	70	ns
$t_r$	Turn-on Rise Time			22	41	
$t_{d(OFF)}$	Turn-off Delay Time			120	210	
$t_f$	Turn-off Fall Time			75	140	
<b>Gate Charge Characteristics</b> <sup>(4)</sup>						
$Q_g$	Total Gate Charge	$V_{DS}=30V, V_{GS}=10V,$ $I_{DS}=40A$		155	220	nC
$Q_{gs}$	Gate-Source Charge			45		
$Q_{gd}$	Gate-Drain Charge			48		

- Notes: ① Pulse width limited by safe operating area.  
 ② Current limited by package( Limitation Current is 75A )  
 ③ Pulse test ; Pulse width $\leq 300\mu s$ , duty cycle $\leq 2\%$ .  
 ④ Guaranteed by design, not subject to production testing.

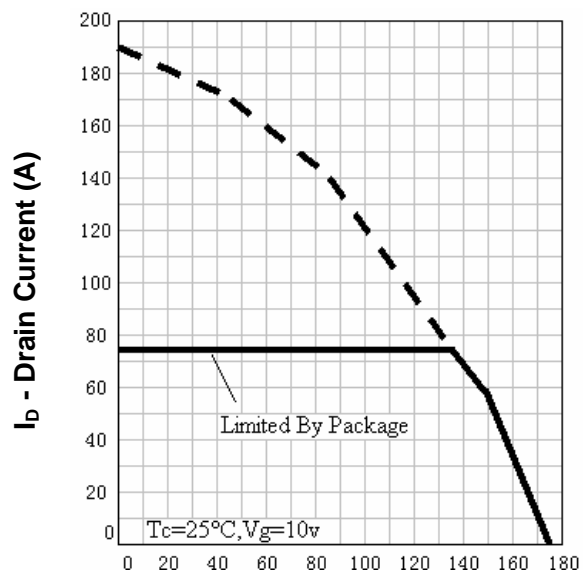
**Typical Characteristics**

**Power Dissipation**



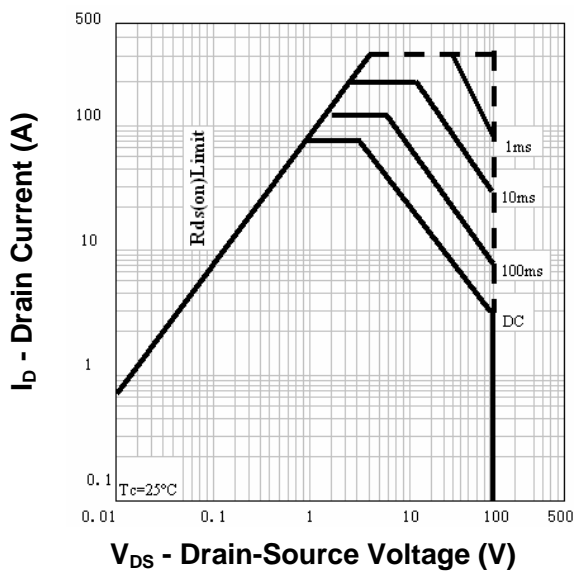
**Tj - Junction Temperature (°C)**

**Drain Current**



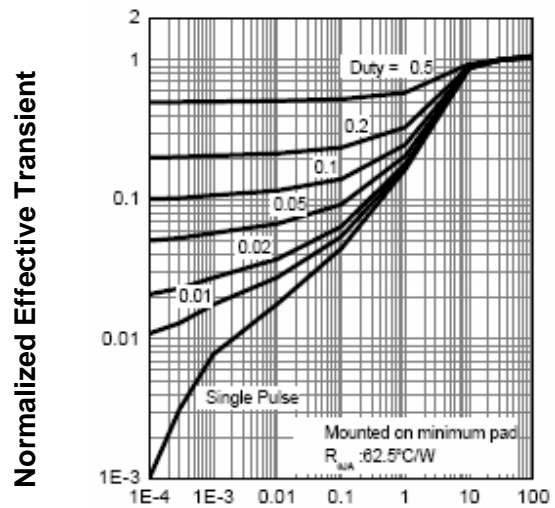
**Tj - Junction Temperature (°C)**

**Safe Operation Area**



**VDS - Drain-Source Voltage (V)**

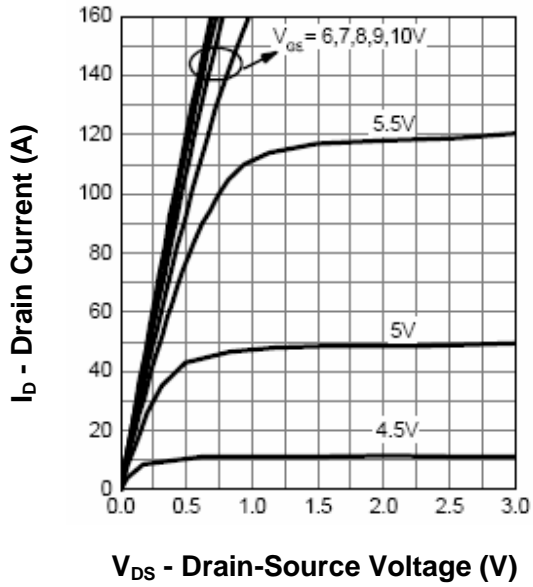
**Thermal Transient Impedance**



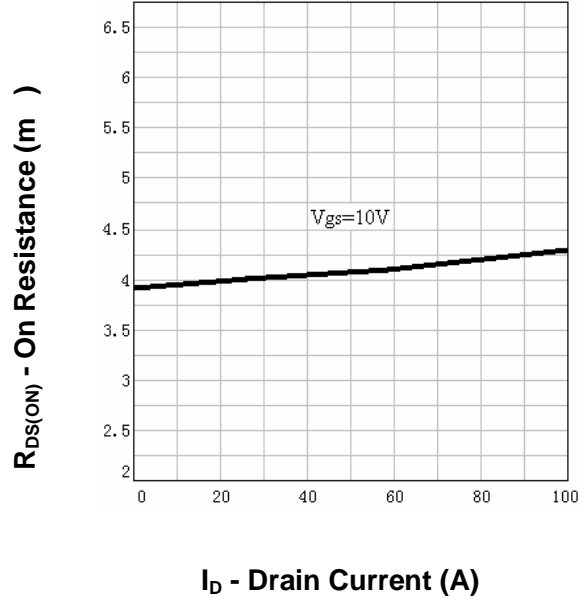
**Square Wave Pulse Duration (sec)**

**Typical Characteristics**

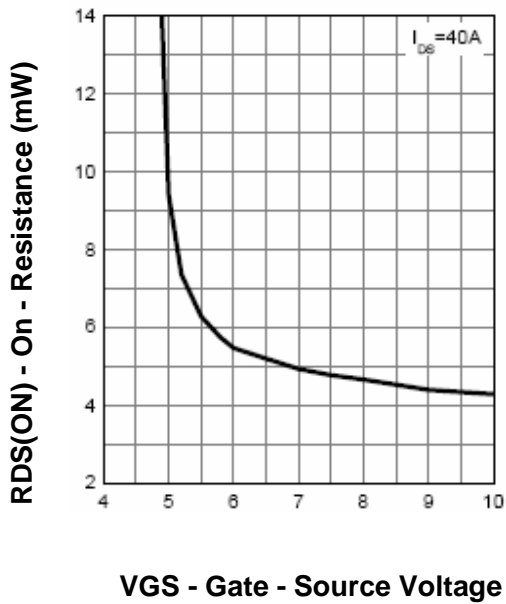
**Output Characteristics**



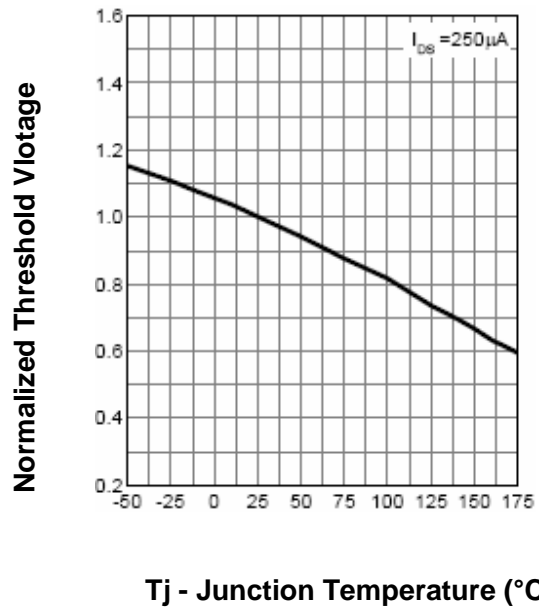
**Drain-Source On Resistance**



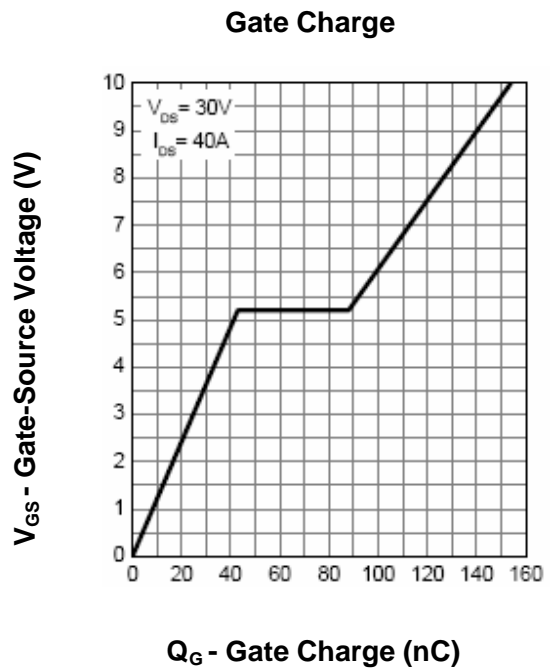
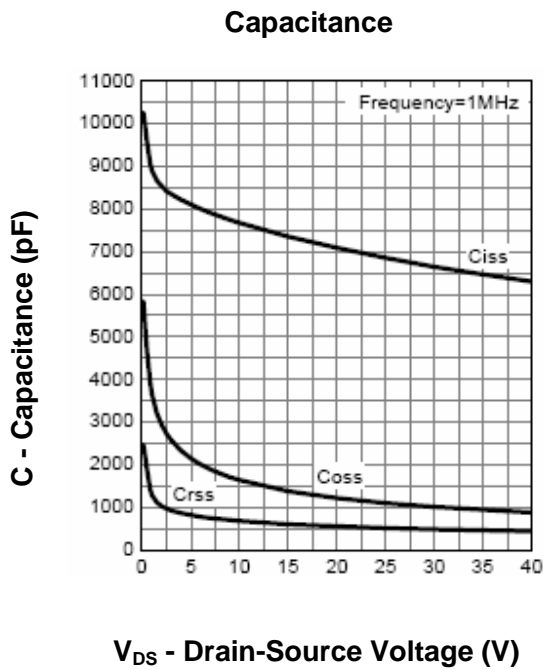
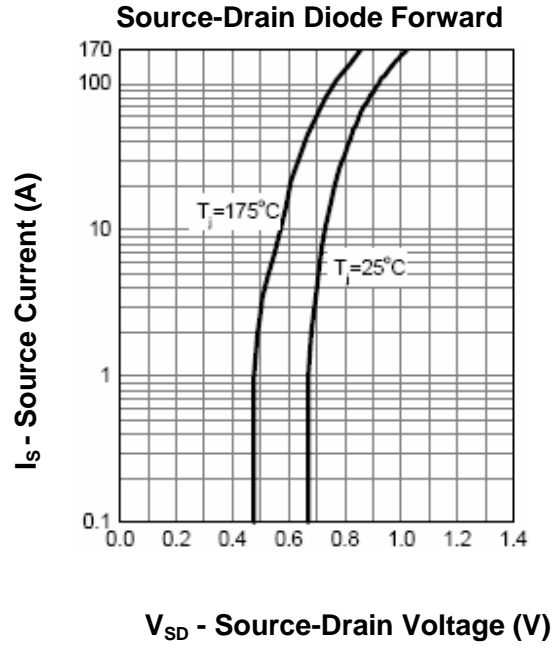
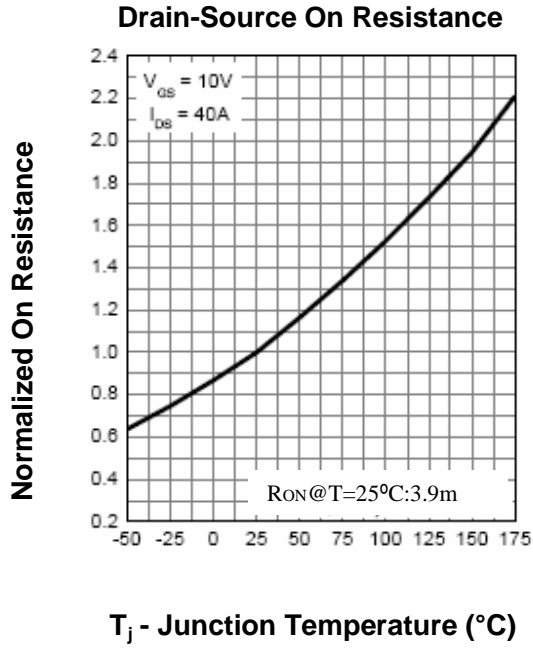
**Drain-Source On Resistance**



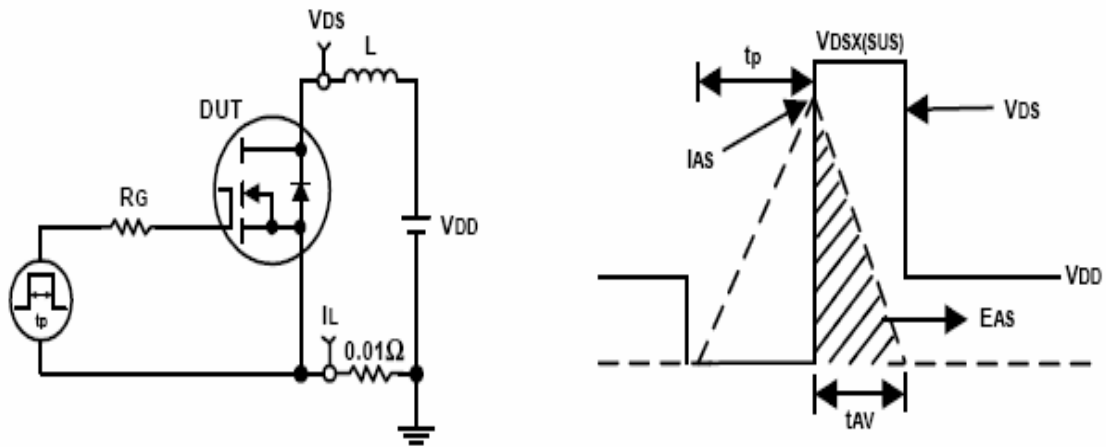
**Gate Threshold Voltage**



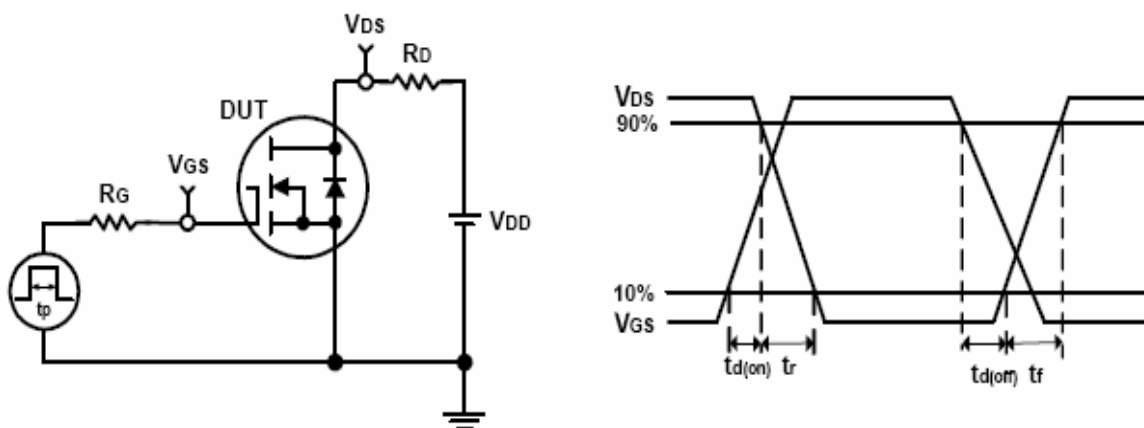
**Typical Characteristics**



**Avalanche Test Circuit and Waveforms**



**Switching Time Test Circuit and Waveforms**



**Ordering and Marking Information****RU190N08****Package (Available)**

Q:TO-247 ; R: TO-220 ; S: TO-263

**Operating Temperature Range**

C : -55 to 175 °C

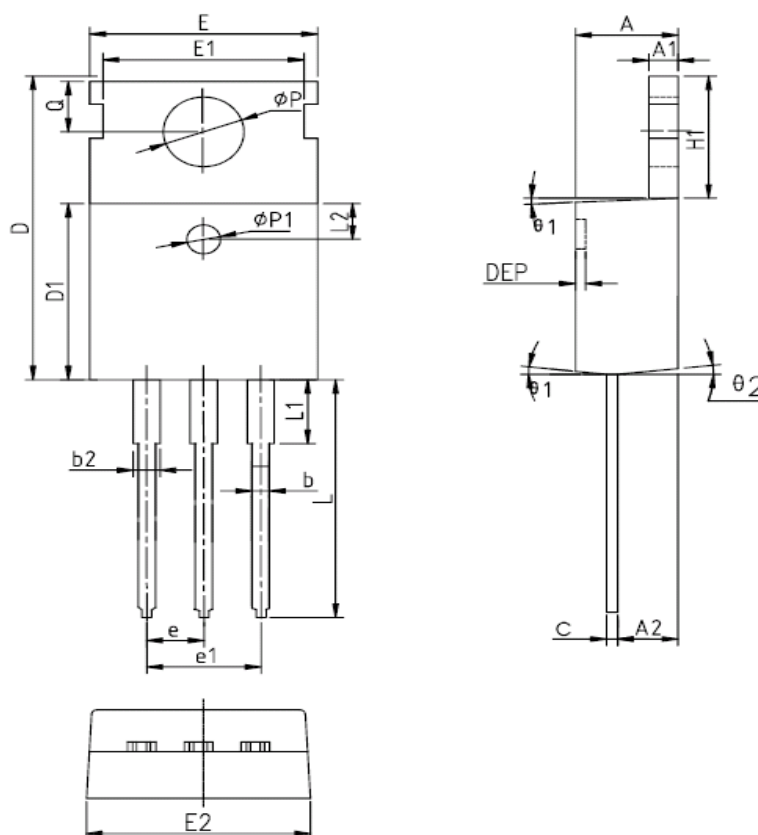
**Assembly Material**

G : Green & Lead Free Device

**Packaging**

T : TUBE

TR : Tape & Reel

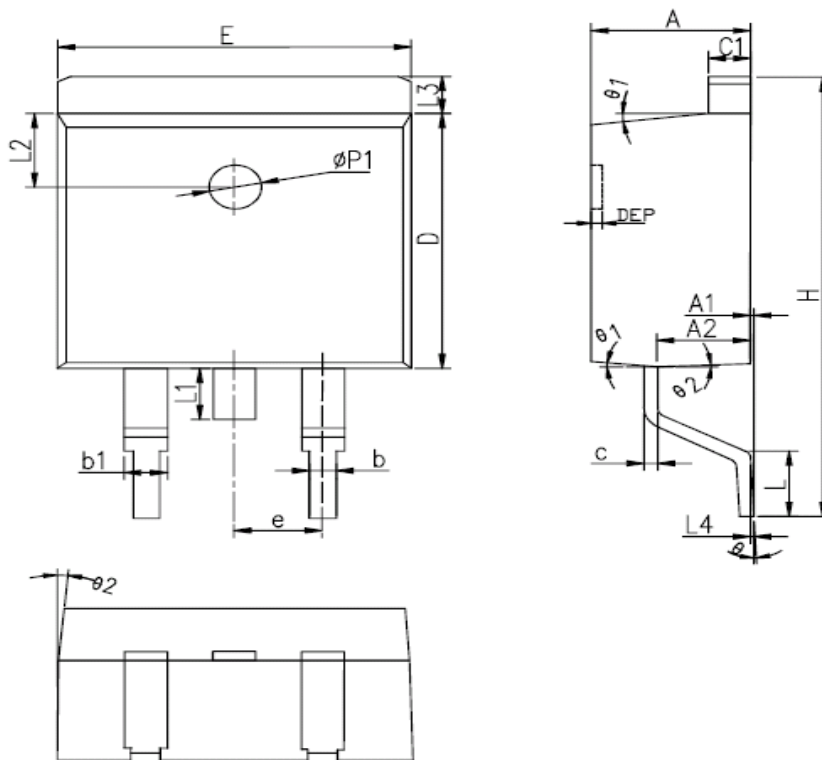
**Package Information**
**TO-220FB-3L**


SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.57	4.70	0.173	0.180	0.185	$\phi p1$	1.40	1.50	1.60	0.055	0.059	0.063
A1	1.27	1.30	1.33	0.050	0.051	0.052	e	2.54BSC			0.1BSC		
A2	2.35	2.40	2.50	0.093	0.094	0.098	e1	5.08BSC			0.2BSC		
b	0.77	-	0.90	0.030	-	0.035	H1	6.40	6.50	6.60	0.252	0.256	0.260
b2	1.23	-	1.36	0.048	-	0.054	L	12.75	-	13.17	0.502	-	0.519
C	0.48	0.50	0.52	0.019	0.020	0.021	L1	-	-	3.95	-	-	0.156
D	15.40	15.60	15.80	0.606	0.614	0.622	L2	2.50REF.			0.098REF.		
D1	9.00	9.10	9.20	0.354	0.358	0.362	$\phi p$	3.57	3.60	3.63	0.141	0.142	0.143
DEP	0.05	0.10	0.20	0.002	0.004	0.008	Q	2.73	2.80	2.87	0.107	0.110	0.113
E	9.70	9.90	10.10	0.382	0.389	0.398	$\theta 1$	5°	7°	9°	5°	7°	9°
E1	-	8.70	-	-	0.343	-	$\theta 2$	1°	3°	5°	1°	3°	5°
E2	9.80	10.00	10.20	0.386	0.394	0.401							

ALL DIMENSIONS REFER TO JEDEC STANDARD  
DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS



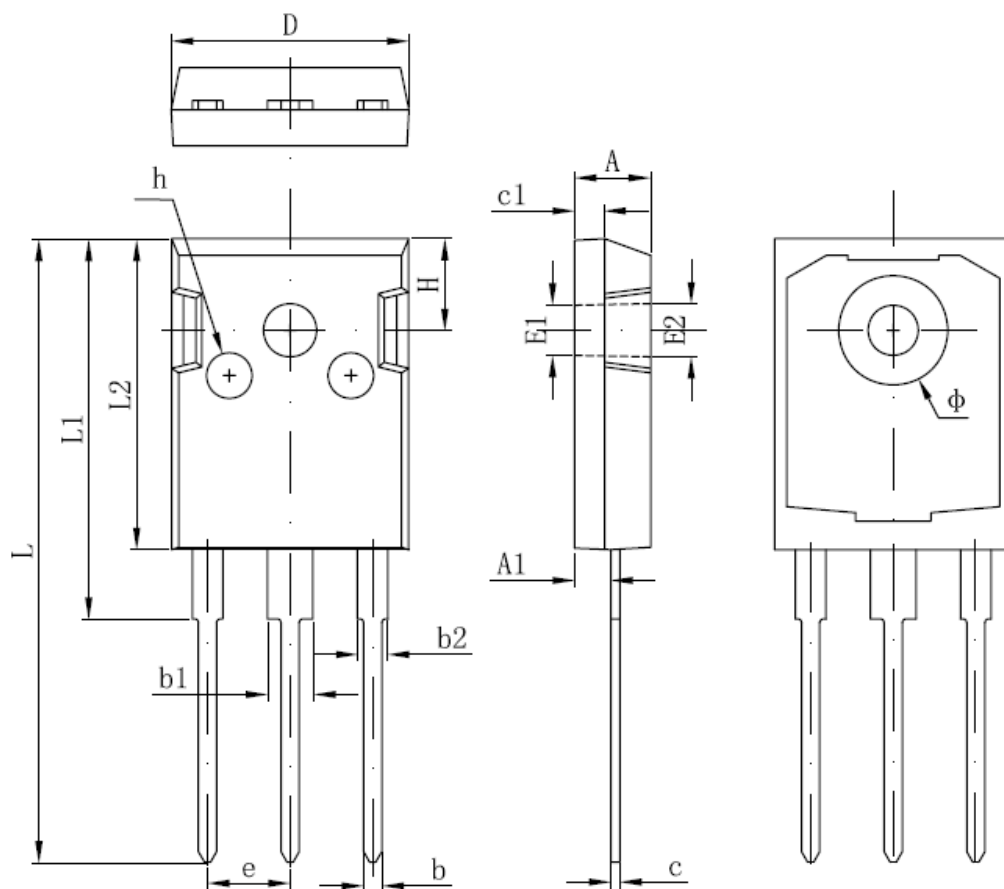
**TO-263-2L**



SYMBOL	MM			INCH			SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX		MIN	NOM	MAX	MIN	NOM	MAX
A	4.40	4.57	4.70	0.173	0.180	0.185	L	2.00	2.30	2.60	0.079	0.090	0.102
A1	0	0.10	0.25	0	0.004	0.010	L3	1.17	1.27	1.40	0.046	0.050	0.055
A2	2.59	2.69	2.79	0.102	0.106	0.110	L1	-	-	1.70	-	-	0.067
b	0.77	-	0.90	0.030	-	0.035	L4	0.25BSC			0.01BSC		
b1	1.23	-	1.36	0.048	-	0.052	L2	2.50REF.			0.098REF.		
c	0.34	-	0.47	0.013	-	0.019	θ	0°	-	8°	0°	-	8°
C1	1.22	-	1.32	0.048	-	0.052	θ 1	5°	7°	9°	5°	7°	9°
D	8.60	8.70	8.80	0.338	0.343	0.346	θ 2	1°	3°	5°	1°	3°	5°
E	10.00	10.16	10.26	0.394	0.4	0.404	DEP	0.05	0.10	0.20	0.002	0.004	0.008
e	2.54BSC			0.1BSC			Øp1	1.40	1.50	1.60	0.055	0.059	0.063
H	14.70	15.10	15.50	0.579	0.594	0.610							

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**TO-247**



SYMBOL	MM		INCH		SYMBOL	MM		INCH	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	4.850	5.150	0.191	0.200	E2	3.600 REF		0.142 REF	
A1	2.200	2.600	0.087	0.102	L	40.900	41.300	1.610	1.626
B	1.000	1.400	0.039	0.055	L1	24.800	25.100	0.976	0.988
b1	2.800	3.200	0.110	0.126	L2	20.300	20.600	0.799	0.811
b2	1.800	2.200	0.071	0.087	$\Phi$	7.100	7.300	0.280	0.287
c	0.500	0.700	0.020	0.028	e	5.450 TYP		0.215 TYP	
c1	1.900	2.100	0.075	0.083	H	5.980 REF.		0.235 REF.	
D	15.450	15.750	0.608	0.620	h	0.000	0.300	0.000	0.012
E1	3.500 REF.		0.138 REF.						

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